



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## LN142WP38

## Square Type

□ 5.0 mm × 2.0 mm

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$ 

- Yellow Green

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	90	mW
Forward current	$I_F$	30	mA
Pulse forward current *	$I_{FP}$	150	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

## ■ Lighting Color

- Yellow Green
- Orange

- Orange

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	90	mW
Forward current	$I_F$	30	mA
Pulse forward current *	$I_{FP}$	150	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +100	$^\circ\text{C}$

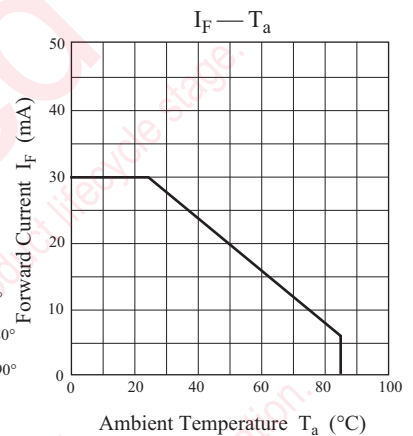
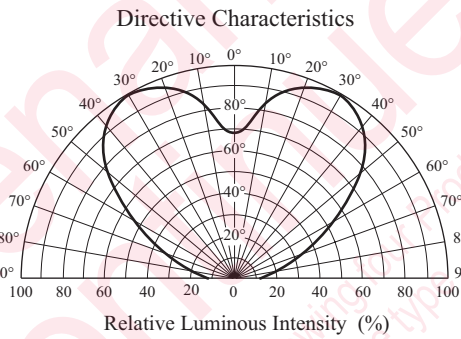
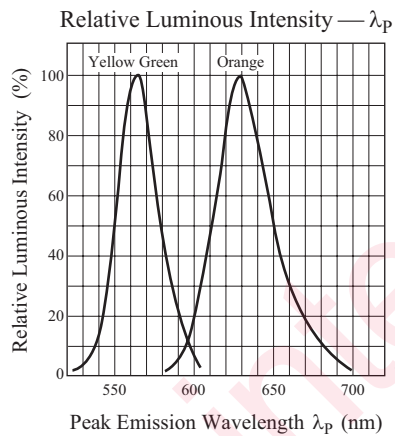
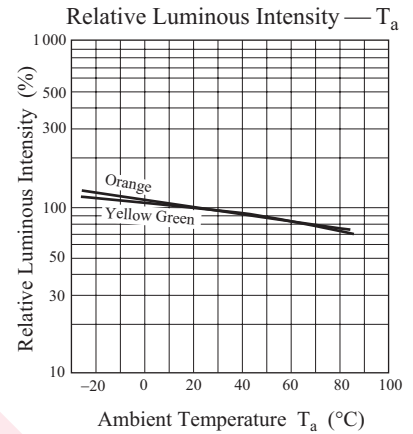
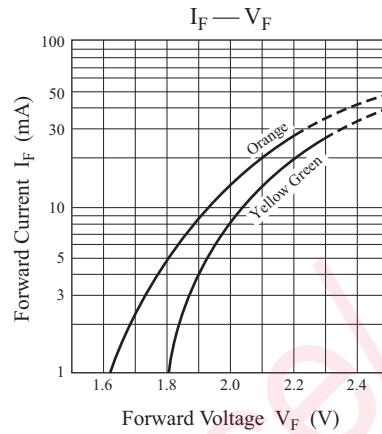
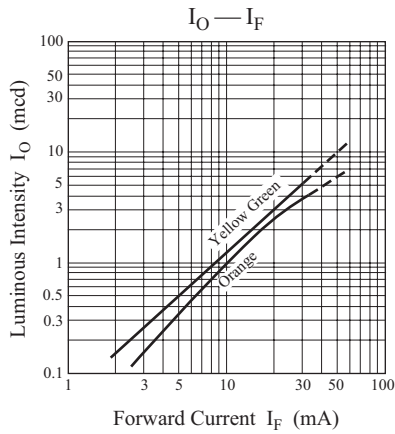
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C}$ 

- Yellow Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		1.0	3.0		mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			10	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 20\text{ mA}$		2.2	2.8	V
Peak emission wavelength	$\lambda_p$	$I_F = 20\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		30		nm

- Orange

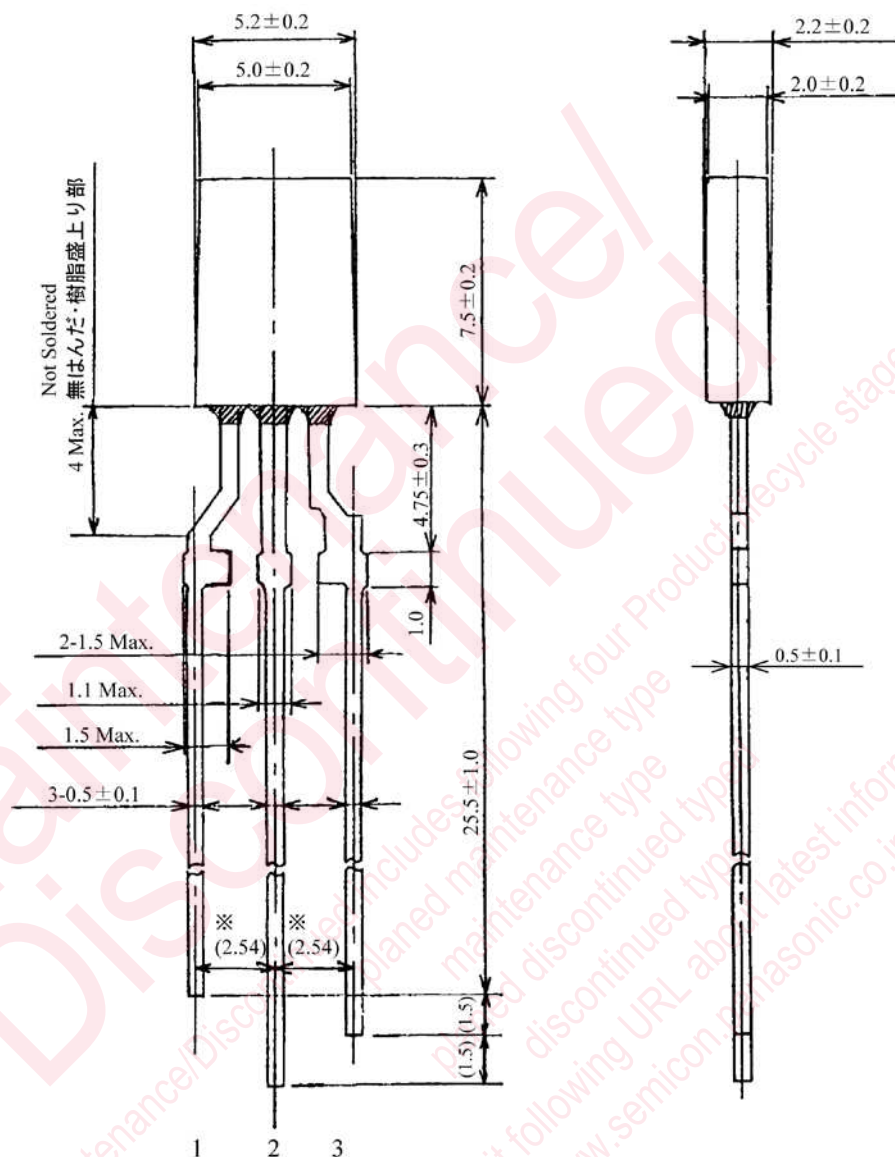
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		1.0	2.5		mcd
Reverse current	$I_R$	$V_R = 3\text{ V}$			10	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 20\text{ mA}$		2.1	2.8	V
Peak emission wavelength	$\lambda_p$	$I_F = 20\text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		40		nm





## ■ Package (Unit: mm)

## LLXFTN3SH422



## 【注意/Notes】

1. 指示無き寸法公差  $\pm 0.2$  mm / Tolerance is  $\pm 0.2$  mm unless otherwise specified.
2. ※リード間寸法は樹脂根元寸法を示す / ※The size between leads shows a resin root size.
3. ( ) 寸法は参考値とする / ( ) A size is a reference.

## ● Pin name

- 1: Anode (Orange)
- 2: Cathode (Common)
- 3: Anode (Yellow Green)

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